



# SLOVENSKI STANDARD

## SIST EN 60249-2-4:1997

01-avgust-1997

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**Base materials for printed circuits - Part 2: Specifications - Specification No.4:  
Epoxide woven glass fabric copper-clad laminated sheet - General purpose grade  
(IEC 249-2-4:1987 + A2:1992)**

Base materials for printed circuits -- Part 2: Specifications -- Specification No. 4: Epoxide woven glass fabric copper-clad laminated sheet, general purpose grade

Basismaterialien für gedruckte Schaltungen -- Teil 2: Einzelbestimmungen -- Einzelbestimmung Nr. 4: Kupferkaschierte Epoxidharz-Glashartgewebetafeln für allgemeine Anwendungszwecke

Matériaux de base pour circuits imprimés -- Partie 2: Spécifications -- Spécification n° 4: Feuille de tissu de verre époxyde recouverte de cuivre, de qualité courante

**Ta slovenski standard je istoveten z: EN 60249-2-4:1994**

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**ICS:**

31.180 Tiskana vezja (TIV) in tiskane Printed circuits and boards  
plošče

**SIST EN 60249-2-4:1997**

**en**

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EUROPEAN STANDARD

EN 60249-2-4

NORME EUROPEENNE

EUROPÄISCHE NORM

February 1994

UDC 621.3.049.75-033.5-41

Supersedes HD 313.2.4 S2:1990

Descriptors: Printed circuit, composite materials, glass, copper

## ENGLISH VERSION

Base materials for printed circuits

Part 2: Specifications

Specification No. 4: Epoxide woven glass fabric  
copper-clad laminated sheet, general purpose grade  
(IEC 249-2-4:1987 + A2:1992)Matériaux de base pour circuits  
imprimés  
Partie 2: Spécifications  
Spécification n° 4: Feuille de  
tissu de verre époxyde  
recouverte de cuivre, de qualité  
couranteBasismaterialien für gedruckte  
Schaltungen  
Teil 2: Einzelbestimmungen  
Einzelbestimmung Nr. 4:  
Kupferkaschierte  
Epoxidharz-Glashartgewebetafeln  
für allgemeine  
Anwendungszwecke

(CEI 249-2-4:1987 + A2:1992)

(IEC 249-2-4:1987 + A2:1992)

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This European Standard was approved by CENELEC on 1993-12-08.

CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

## CENELEC

European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B-1050 Brussels

### FOREWORD

The text of the International Standard IEC 249-2-4:1987 and its amendment 2:1992 (including amendment 1:1989) was submitted to the CENELEC formal vote for acceptance as a Harmonization Document.

The draft was approved by CENELEC as HD 313.2.4 S3 on 6 July 1993 and was immediately submitted to a new vote for conversion into a European Standard.

The text of the International Standard was approved by CENELEC as EN 60249-2-4 on 8 December 1993.

The following dates were fixed:

- latest date of publication of an identical national standard (dop) 1995-03-15
- latest date of withdrawal of conflicting national standards (dow) 1995-03-15

Annexes designated "normative" are part of the body of the standard. In this standard, annex ZA is normative.

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### ENDORSEMENT NOTICE

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The text of the International Standard IEC 249-2-4:1987 and its amendment 2:1992 (including amendment 1:1989) was approved by CENELEC as a European Standard without any modification.



## ANNEX ZA (normative)

OTHER INTERNATIONAL PUBLICATIONS QUOTED IN THIS STANDARD  
WITH THE REFERENCES OF THE RELEVANT EUROPEAN PUBLICATIONS

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies.

NOTE : When the international publication has been modified by CENELEC common modifications, indicated by (mod), the relevant EN/HD applies.

| IEC<br>Publication | Date | Title   | EN/HD       | Date |
|--------------------|------|---|-------------|------|
| -----              | ---- | -----   | -----       | ---- |
| 249-1              | 1982 | Base materials for printed circuits<br>Part 1: Test methods   | EN 60249-1* | 1993 |
| 249-3A             | 1976 | Part 3: Special materials used in<br>connection with printed circuits<br>First supplement: Specification No. 2:<br>Specification for copper foil for use in<br>the manufacture of copper-clad base<br>materials | -           | -    |

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\* EN 60249-1 includes A1:1984 + A2:1989 + A3:1991 to IEC 249-1

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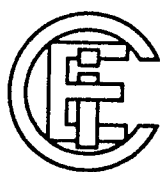
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# NORME INTERNATIONALE INTERNATIONAL STANDARD

CEI  
IEC  
249-2-4

Deuxième édition  
Second edition  
1987



Commission Electrotechnique Internationale

International Electrotechnical Commission

Международная Электротехническая Комиссия

## Matériaux de base pour circuits imprimés

Deuxième partie: Spécifications

Spécification n° 4: Feuille de tissu de verre époxyde recouverte de cuivre,  
de qualité courante

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## Base materials for printed circuits

Part 2: Specifications

Specification No. 4: Epoxide woven glass fabric  
copper-clad laminated sheet, general purpose grade

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

## BASE MATERIALS FOR PRINTED CIRCUITS

## Part 2: Specifications

Specification No. 4: Epoxide woven glass fabric copper-clad laminated sheet,  
general purpose grade

## FOREWORD

- 1) The formal decisions or agreements of the IEC on technical matters, prepared by Technical Committees on which all the National Committees having a special interest therein are represented, express, as nearly as possible, an international consensus of opinion on the subjects dealt with.
- 2) They have the form of recommendations for international use and they are accepted by the National Committees in that sense.
- 3) In order to promote international unification, the IEC expresses the wish that all National Committees should adopt the text of the IEC recommendation for their national rules in so far as national conditions will permit. Any divergence between the IEC recommendation and the corresponding national rules should, as far as possible, be clearly indicated in the latter.
- 4) The IEC has not laid down any procedure concerning marking as an indication of approval and has no responsibility when an item of equipment is declared to comply with one of its recommendations.

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## PREFACE

This standard has been prepared by IEC Technical Committee No. 52: Printed Circuits.

This second edition replaces the first edition of Specification No. 4 which was included in IEC Publication 249-2.

This standard forms Specification No. 4 of a publication series which will replace the specifications originally included in IEC Publication 249-2 and will also include new specifications.

The text of this standard is based on the following documents:

| Six Months' Rule | Report on Voting | Two Months' Procedure | Report on Voting |
|------------------|------------------|-----------------------|------------------|
| 52(CO)239        | 52(CO)268        | 52(CO)254             | 52(CO)282        |

Further information can be found in the relevant Reports on Voting indicated in the table above.

The following IEC publications are quoted in this standard:

- Publications Nos. 249-1 (1982): Base Materials for Printed Circuits, Part 1: Test Methods.  
 249-3A (1976): Part 3: Special materials used in connection with printed circuits. First supplement:  
 Specification No. 2: Specification for copper foil for use in the manufacture of  
 copper-clad base materials.

## BASE MATERIALS FOR PRINTED CIRCUITS

### Part 2: Specifications

#### Specification No. 4: Epoxide woven glass fabric copper-clad laminated sheet, general purpose grade

##### 1. Scope

This specification gives requirements for properties of epoxide woven glass fabric copper-clad laminated sheet, general purpose grade, in thicknesses of 0.5 mm up to 6.4 mm.

*Note.* — To designate this material, the reference: 249-2-4-IEC-EP-GC-Cu may be used; if there is no risk of confusion, the type designation may be abbreviated to read IEC-249-2-4.

##### 2. Materials and construction

The sheet consists of an insulating base with metal foil bonded to one or both sides.

###### 2.1 Insulating base

Epoxide resin bonded woven glass fabric laminate.

###### 2.2 Metal foil

Copper as specified in IEC Publication 249-3A: First Supplement to Publication 249-3: Base Materials for Printed Circuits, Part 3: Special Materials Used in Connection with Printed Circuits — Specification No. 2: Specification for Copper Foil for Use in the Manufacture of Copper-clad Base Materials.

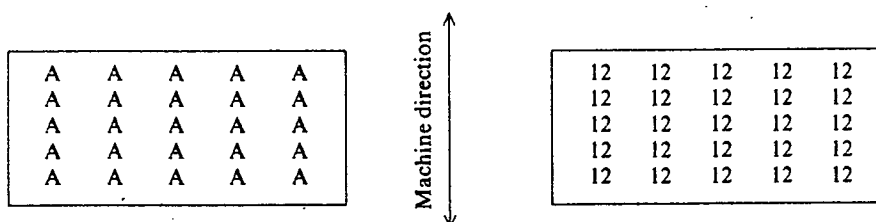
The preferred foils are Type A (electro-deposited copper) of standard ductility.

##### 3. Internal marking

Each sheet should bear a manufacturer's identification mark that is:

- in black or some other colour not to be confused with red (red colour shall not be used as this indicates a material of defined flammability);
- repeated at intervals so that no part of the sheet is further than 75 mm (3 in) from the furthest point of the nearest mark;
- printed so as to indicate the machine direction of the filling material; if letters or numbers are used, these shall be upright in the machine direction.

Examples:



## 4. Electrical properties

TABLE I

| Property  | Test method<br>(Sub-clause<br>of IEC<br>Publication 249-1)* | Requirement  |
|---|---|--|
| Resistance of foil  | 2.1   | As specified in IEC Publication 249-3A                                 |
| Surface resistance while in the humidity chamber (optional) | 2.2   | 10 000 M $\Omega$ min.   |
| Surface resistance after recovery                           | 2.2   | 50 000 M $\Omega$ min.   |
| Volume resistivity while in the humidity chamber (optional) | 2.3   | 5 000 M $\Omega$ m min.  |
| Volume resistivity after recovery                           | 2.3   | 10 000 M $\Omega$ m min.   |
| Surface corrosion   | 2.4   | No visible corrosion products in the gap                               |
| Corrosion at the edge                                       | 2.5   | Positive pole: not worse than A/B<br>Negative pole: not worse than 1.4 |
| Relative permittivity after damp heat and recovery          | 2.7   | The average value shall not exceed 5.5                                 |
| Dielectric dissipation factor after damp heat and recovery  | 2.7   | The average value shall not exceed 0.035                               |
| Surface resistance at 125 °C                                | 2.9.1   | 1 000 M $\Omega$ min.  |
| Volume resistivity at 125 °C                                | 2.9.1   | 1 000 M $\Omega$ m min.  |

\* Base Materials for Printed Circuits, Part 1: Test Methods.

## 5. Non-electrical properties of the copper-clad sheet

## 5.1 Appearance of the copper-clad face

## 5.1.1 Normal surface finish

The copper-clad face shall be substantially free from blisters, wrinkles, pinholes, deep scratches, pits and resin. Any discoloration or contamination shall be readily removable with a hydrochloric acid solution of density 1.02 g/cm<sup>3</sup> or with a suitable organic solvent.

## 5.1.2 High-quality surface finish (optional)

If a surface of high quality is essential for precious metal plating or fine line etching and is ordered by the purchaser, the following requirements shall apply in addition to those of Sub-clause 5.1.1 when inspected in accordance with Sub-clause 3.9 of IEC Publication 249-1.

The surface finish of the copper-clad face shall be such as not to conceal imperfections.